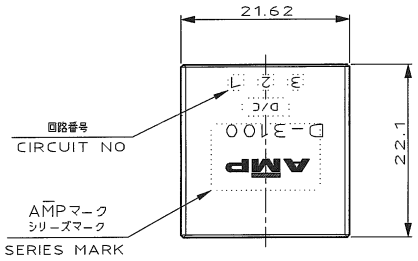

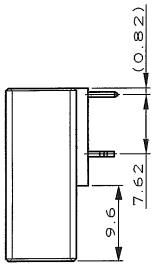

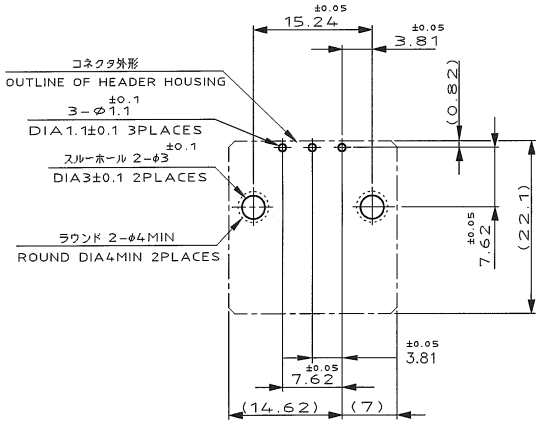

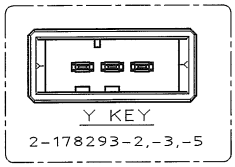

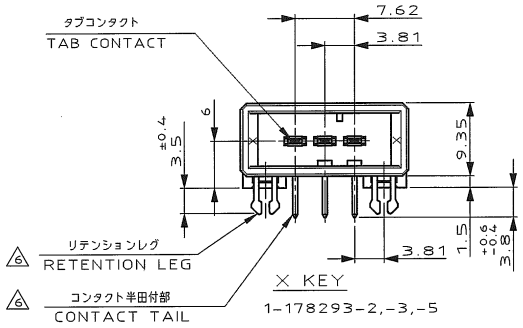

推奨基板取付け穴寸法
PC 基板厚:1.6±0.1
(非累積公差)
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
PC BOARD THICKNESS:1.6±0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)

NOTES

1. MATERIAL:HOUSING:GLASS FILED THERMO PLASTIC,POLYESTER
CONTACT:COPPER ALLOY
RETENTION LEG:COPPER ALLOY
2. FINISH(CONTACT AREA):0.38μmMIN GOLD PLATING OVER Ni PLATING
3. FINISH(CONTACT AREA):0.76μmMIN GOLD PLATING OVER Ni PLATING
4. FINISH(CONTACT AREA):2.0 μmMIN TIN PLATED OVER NICKEL
~~5. FINISH(RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL~~
6. FINISH(RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

注 記

1. 材料: ハウジング: ガラス入り熱可塑性
ポリエステル樹脂
コンタクト: 銅合金
リテンションレグ: 銅合金
2. めっき: コンタクト: 全面Ni下地
接触部:0.38μm MIN金めっき
3. めっき: コンタクト: 全面Ni下地
接触部:0.76μm MIN金めっき
4. めっき: コンタクト: 全面Ni下地
接触部:2.0 μm MINスズめっき
~~5. めっき: リテンションレグとコンタクト半田付部 : ニッケル下地の上に半田めっき~~
6. めっき:リテンションレグとコンタクト半田付部 : ニッケル下地の上にスズめっき

6	4	1,2-178293-5
6	3	1,2-178293-3
6	2	1,2-178293-2
(FINISH)		製品番号 (PART NO.)

LTR	REVISION RECORD	DR	CHK	DATE
C1	REVISED PER ECO-11-005030	RK	HMR	14APR 11

TE Connectivity

WIRE RANGE ~~mm²(AWG -)~~	INSULATION DIA ~~- mmφ~~
MATERIAL SEE NOTE 注記参照	FINISH SEE NOTE 注記参照
DR. 20/MAR/'95 K.IKEDA	DE. 20/MAR/'95 K.IKEDA
CHK. 23.MAR'92 S.MANABE	APP. 23.MAR'92 S.MANABE

NAME: 3 POS SINGLE ROW HORIZONTAL HDR ASS'Y FOR DYNAMIC 3100

一般公差 (GENERAL TOLERANCE)
10以下 : ±0.3
10を超え 30以下 : ±0.4
30を超え100以下 : ±0.5
角度 : ±3°

SIZE	LOC	NUMBER
A3	J	C-178293
SCALE 2-1	REV. C1	SHEET 1 OF 1

(CUSTOMER DRAWING) 顧客用図面

NUMBER 178293
3rd ANGLE PROJECTION
METRIC
DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT
PRINT DIST

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